

Orbotech Diamond[™] 10T/10TXL

Solder Mask at its Best

Orbotech Diamond™ 10T/10TXL

Orbotech Diamond 10T/10TXL is an advanced high-capacity digital imaging (DI) solution exclusively designed to meet the unique demands and challenges of thick solder mask applications. The field-proven Orbotech Diamond 10T/10TXL is a dedicated system for thick solder mask that delivers high throughput and high-quality imaging, while addressing strict undercut requirements. Powered by KLA's proprietary SolderFast™ technology, Orbotech Diamond 10T/10TXL raises the DI bar for thick solder mask applications, enhancing imaging accuracy and quality, while decreasing total cost of ownership (TCO).



Benefits

High-Quality Imaging and High Throughput

- Patented, high power illumination source
- 3-wavelength spectrum for high-quality sidewalls, minimal undercuts and excellent surface quality
- One-pass technology to cover full panel area at one scan with uniform imaging of the entire panel area
- On-the-fly target recognition and acquisition capabilities
- High depth-of-focus (DOF) for challenging topographies
- Specially designed illumination source to address the unique undercut demands of thick SM applications

High Capacity

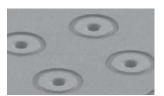
- Fast and easy SM imaging set-up for new jobs
- Dual-table transport mechanism for optimal imaging time and efficiency
- Optional clamping solution
- Industry 4.0 and automation-ready solution

Outstanding Imaging Accuracy

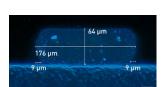
- Registration accuracy as fine as ± 10µm
- Advanced scaling modes and algorithms for challenging panel distortions

Low Total Cost of Ownership

- High production system efficiency
- Long-life LEDs
- Low power consumption



High-quality SM imaging, no residue on vias



>60µm SM thickness on prepreg



High registration accuracy

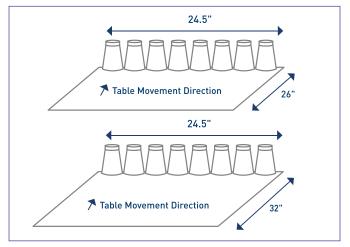


100µm solder dam, 40µm SM thickness on prepreg

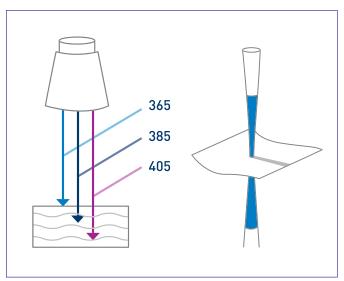




High-Quality Imaging and High Throughput

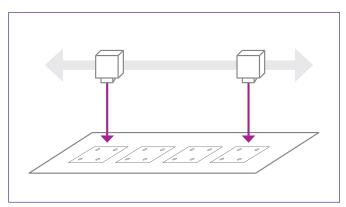


One pass printing for high throughput, high uniformity and no stitiching



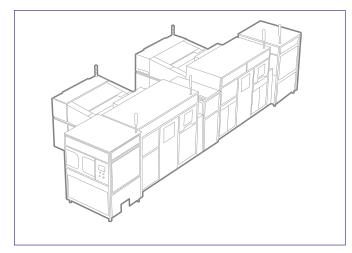
3WL spectrum for high-quality side walls, minimal undercut and excellent surface quality

High depth-of-focus (DOF) for challenging topographies

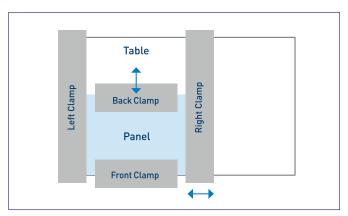


On-the-fly target recognition and acquisition

High-Capacity Mass Production Solution



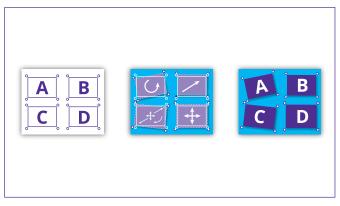
Automation ready solution



Clamping

Outstanding Imaging Accuracy

Advanced scaling modes and algorithms for challenging panel distortions include auto scaling, partial scaling and non-linear scaling



CAM data



Specifications

Orbotech Diamond 10T

Orbotech Diamond 10TXL

Minimum SRO*	75µm	
Minimum Dam Size*		
Minimum Dam Size	50µm	
Registration Accuracy**	±10μm	
Maximum Panel Area (X/Y)	25" x 26" (635mm x 660mm)	25" x 32" (635mm x 812mm)
Maximum Panel Area (X/Y) with Clamping	24.5" x 23" (622mm x 584mm)	24.5" x 30" (622mm x 762mm)
Maximum Exposure Area (X/Y)	24.5" x 26" (622mm x 660mm)	24.5" x 32" (622mm x 812mm)
Maximum Exposure Area (X/Y) with Clamping	24" x 22.5" (609mm x 571mm)	24" x 29.5" (609mm x 749mm)
Exposure Energy Range	50-2,200mJ/cm ²	
Dimensions	Height: 1,960mm Depth: 3,226mm Width: 1,900mm	Height: 1,960mm Depth: 3,315mm Width: 1,900mm
Weight	5,000Kg	
Clamping	Optional	
Application	Solder mask exposure	

^{*}Dependent on solder resist type and process ** All values are 3σ

The above specifications are subject to change without notification.